



C-VII: Microjoining and Nanojoining

Draft Agenda (Update: June 21th, 2025)

78th Annual Assembly 2025, Genoa

VII-0280-25

Authors: Jolanta JANCZAK-RUSCH

Comments: Face-to-Face Meeting

Agenda for 78th Annual Assembly and International Conference Meeting

Monday June 23rd, 14:20-18:00

Room: Levante

Session I-1, Chair: Jolanta Janczak-Rusch, Tomokazu Sano

Time	Agenda Item/Presentation Title (Abstract No.)	Presenter	Document
14:20-14:40	Opening: welcome and introduction Approval of Minutes 2024	Jolanta Janczak-Rusch	
14:20-14:40	Methodology development for Pressure-less Low-Temperature Sintering Using Nano-Ag Precursor Pastes CANCELLED	Cheng Zhang, Chemnitz Uni. of Tech., MAHLE Int. GmbH	VII-0281-25
14:40-15:00	Ultrasound Powered Liquid Metal Filling the Ultrafine Channel for Flexible Electronics	Zirong Xu Harbin Institute of Technology, China	VII-0282-25
15:00-15:20	The pressure balance effect of the polytetrafluoroethylene buffer film in pressure-assisted sintering bonding	Chenxiao Huang Tsinghua University, China	VII-0283-25
15:20-15:40	High-performance Laser-assisted Joining of Carbon Fiber-reinforced Polyetheretherketone	Guan Yingchun Beihang University, China	VII-0284-25
15:45-16:15	Coffee Break		

Session I-2, Chair: Lei Liu, Ting Huang

Time	Agenda Item/Presentation Title	Presenter	Document
16:15-16:35	Selective Electrodeposition of Copper Arrays: A Promising Solution for Advanced Microelectronics Interconnection	Hongtao Chen Harbin Institute of Technology, China	VII-0285-25
16:35-16:55	MoS2/ZnO-heterostructured optoelectronic synapse fabricated by femtosecond laser nanojoining	Zehua Li Tsinghua University, China	VII-0286-25
16:55-17:15	Wetting Constrained Conformal Soldering Technology for Complex Structure Interconnection Based on Metal Aerogel	Wenbo Zhu Harbin Institute of Technology, China	VII-0287-25
17:15-17:35	Neurocomputing based on heterogeneous integration of Nanomaterials	Jinpeng Huo Tsinghua University, China	VII-0288-25
17:35-17:55	Two-step Plasma-activated Strategy for the LiTaO3/Sapphire Low-temperature Bonding	Linjie Liu Harbin Institute of Technology, China	VII-0301-25

Tuesday June 24th, 8:30-12:30, Room: Levante
Joint meeting of C-VII Microjoining and Nanojoining and
C-XVII on Brazing, Soldering and Diffusion Bonding with Nanomaterials

Session II-1, Chair: Huaping Xiong, Jolanta Janczak-Rusch

Time	Agenda Item/Presentation Title	Presenter	Document
8:30-8:50	Opening of Joint C-VII and C-XVIII Meeting Welcome and Introduction to the Commissions	Jolanta Janczak-Rusch and Huaping Xiong	
8:50-9:00	WitW Introduction	Prof. Norbert Enzinger (Editor)	
9:00-9:10	IIW-SEC Visit	Elisabetta Sciacccaluga	
9:10-9:30	Joining of alumina ceramics with Ti and Zr interlayers by spark plasma sintering	Gurdial Blugan Empa. Switzerland	VII-0289-25 XVIIA-0355-25
9:30-9:50	Transient High-Temperature Brazing of Carbon-Based Materials and Study of Their Structural and Functional Properties CANCELLED	Yan Yaotian Harbin Institute of Technology, China	VII-0290-25 XVIIA-0356-25
9:50-10:10	Synchronous improvement of mechanical properties and heat transfer performance of diamond/Cu joint achieved by ultrafast laser surfacer ablation	Xinfei Zhang Harbin Institute of Technology, China	VII-0291-25 XVIIA-0357-25
10:15-10:45	Coffee Break		

Session II-2, Chair: Lukas Wojarski, Tomokazu Sano

Time	Agenda Item/Presentation Title	Presenter	Document
10:45-11:05	Brazing of ceramic matrix composite and superalloy assisted with cold spray additive manufacturing	Pengcheng Wang	XVIIA-0359-25 VII-0293-25
11:05-11:25	Liquid Metal Electrohydrodynamic High-Precision Printing Technology and Applications	Jiayun Feng Harbin Institute of Technology, China	VII-0294-25 XVIIA-0360-25
11:25-11:45	The research on design of the Ti-based filler for brazing TA32 honeycomb structure and its mechanical properties	Yongjuan Jing	XVIIA-0361-25 VII-0295-25
11:45-12:05	Evaluation of Fracture Morphology of Al/Cu Joints for Development of Separation Techniques for Joining Dissimilar Materials	Tomo Ogura Osaka University, Japan	VII-0292-25 XVIIA-0358-25
12:05-12:25	Miscellaneous: Future joint meeting in IIW AA, International Conferences, Intermediate meeting, etc. Discussions and Closing Remarks: submission of documents, paper recommendations to WITW, etc.	Huaping Xiong and Jolanta Janczak-Rusch	
12:30-14:00	Lunch Break		

Tuesday June 24th, 14:00-18:00**Room: Levante****Session III-1, Chair: Hiroaki Tatsumi, Jiayun Feng**

Time	Agenda Item/Presentation Title (Abstract No.)	Presenter	Document
14:00-14:20	Molecular Dynamics Investigation of Void Closure in Cu–Cu Bonding with Nanocrystalline and Nanotwinned Structures	Hiroaki Tatsumi Osaka University, Japan	VII-0296-25
14:20-14:40	Interfacial Bonding Mechanism in Femtosecond Laser-Induced Direct Writing of Copper Patterns on Glass Substrates	Zheng Zhou Beijing University of Technology, China	VII-0297-25
14:40-15:00	Process-Microstructure-Property Relationships in Laser Welding of Additively Manufactured High-Temperature Titanium Alloy Lattice Structures	Cheng Liu Shanghai Jiao Tong University, China	VII-0298-25
15:00-15:20	Quasi-in-situ EBSD study on current-induced solder evolution at extreme temperature	Xiaojiu Tang Harbin Institute of Technology, China	VII-0299-25
15:20-15:40	Water vapor assisted free radical activation for direct bonding of silicon-based materials	Xiaohui Yuan Harbin Institute of Technology, China	VII-0300-25
15:45-16:15	Coffee Break		

Session III-2, Chair: Tomo Ogura

Time	Agenda Item/Presentation Title	Presenter	Document
16:15-16:35	Update Best Practice discussion	Tomokazu Sano	
16:35-16:55	Emerging Technologies discussion	Jolanta Janczak-Rusch	
16:55-17:15	Miscellaneous: NMJ2025 conference, intermediate Meeting and joint meetings Closing remarks	Jolanta Janczak-Rusch	
17:15-17.20	End of Meeting	All	